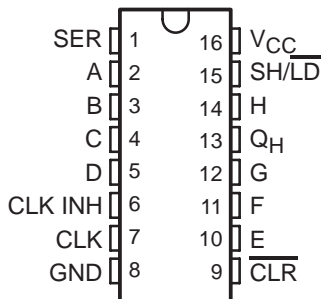


# SN54LV166A, SN74LV166A 8-BIT PARALLEL-LOAD SHIFT REGISTERS

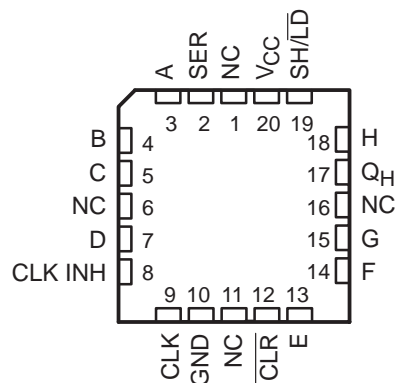
SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

- 2-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 10.5 ns at 5 V
- Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2.3 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Partial-Power-Down-Mode Operation
- Synchronous Load
- Direct Overriding Clear
- Parallel-to-Serial Conversion
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

SN54LV166A . . . J OR W PACKAGE  
SN74LV166A . . . D, DB, DGV, NS, OR PW PACKAGE  
(TOP VIEW)



SN54LV166A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'LV166A devices are 8-bit parallel-load shift registers, designed for 2-V to 5.5-V  $V_{CC}$  operation.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC – D	Tube of 40	SN74LV166AD	LV166A
		Reel of 2500	SN74LV166ADR	
	SOP – NS	Reel of 2000	SN74LV166ANSR	74LV166A
	SSOP – DB	Reel of 2000	SN74LV166ADBR	LV166A
	TSSOP – PW	Tube of 90	SN74LV166APW	LV166A
		Reel of 2000	SN74LV166APWR	
Reel of 250		SN74LV166APWT		
TVSOP – DGV	Reel of 2000	SN74LV166ADGVR	LV166A	
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV166AJ	SNJ54LV166AJ
	CFP – W	Tube of 150	SNJ54LV166AW	SNJ54LV166AW
	LCCC – FK	Tube of 55	SNJ54LV166AFK	SNJ54LV166AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2005, Texas Instruments Incorporated

# SN54LV166A, SN74LV166A

## 8-BIT PARALLEL-LOAD SHIFT REGISTERS

SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

### description/ordering information (continued)

The 'LV166A parallel-in or serial-in, serial-out registers feature gated clock (CLK, CLK INH) inputs and an overriding clear ( $\overline{\text{CLR}}$ ) input. The parallel-in or serial-in modes are established by the shift/load ( $\text{SH}/\overline{\text{LD}}$ ) input. When high,  $\text{SH}/\overline{\text{LD}}$  enables the serial (SER) data input and couples the eight flip-flops for serial shifting with each clock (CLK) pulse. When low, the parallel (broadside) data inputs are enabled, and synchronous loading occurs on the next clock pulse. During parallel loading, serial data flow is inhibited. Clocking is accomplished on the low-to-high-level edge of CLK through a 2-input positive-NOR gate, permitting one input to be used as a clock-enable or clock-inhibit function. Holding either CLK or CLK INH high inhibits clocking; holding either low enables the other clock input. This allows the system clock to be free running, and the register can be stopped on command with the other clock input. CLK INH should be changed to the high level only when CLK is high.  $\overline{\text{CLR}}$  overrides all other inputs, including CLK, and resets all flip-flops to zero.

These devices are fully specified for partial-power-down applications using  $I_{\text{off}}$ . The  $I_{\text{off}}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE

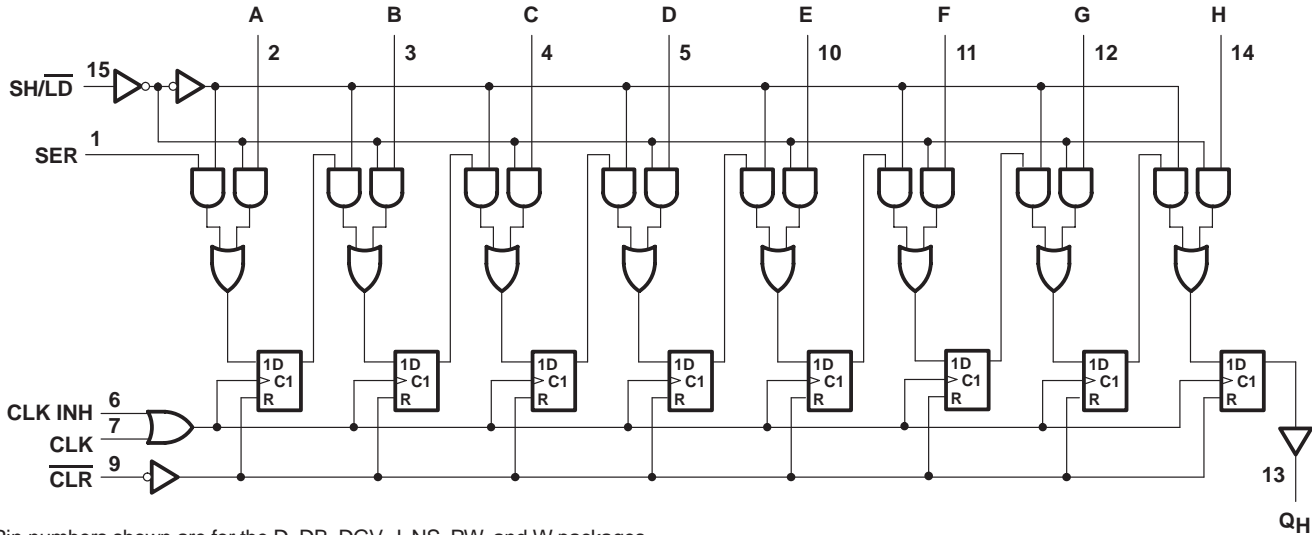
INPUTS						OUTPUTS		
						INTERNAL		QH
$\overline{\text{CLR}}$	$\text{SH}/\overline{\text{LD}}$	CLK INH	CLK	SER	PARALLEL A . . . H	QA	QB	
L	X	X	X	X	X	L	L	L
H	X	L	L	X	X	QA0	QB0	QH0
H	L	L	↑	X	a . . . h	a	b	h
H	H	L	↑	H	X	H	QAn	QGn
H	H	L	↑	L	X	L	QAn	QGn
H	X	H	↑	X	X	QA0	QB0	QH0



# SN54LV166A, SN74LV166A 8-BIT PARALLEL-LOAD SHIFT REGISTERS

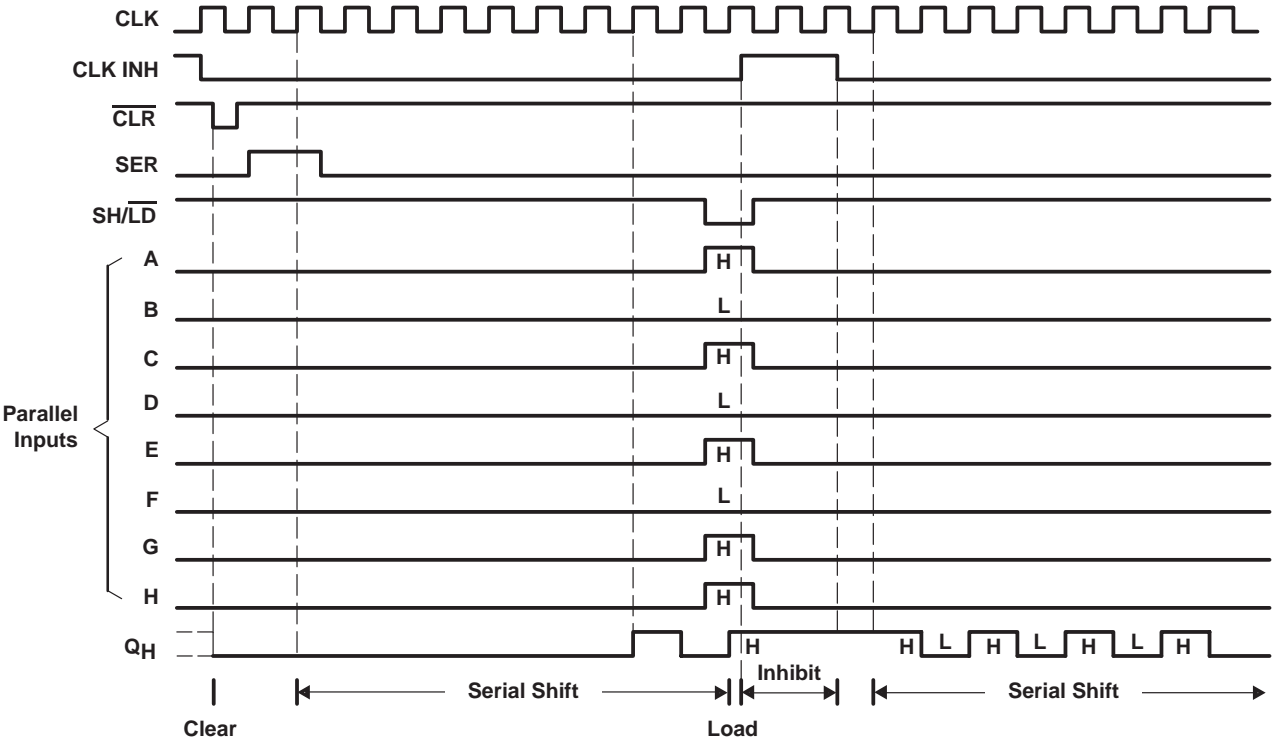
SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

**logic diagram (positive logic)**



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

**typical clear, shift, load, inhibit, and shift sequence**



# SN54LV166A, SN74LV166A

## 8-BIT PARALLEL-LOAD SHIFT REGISTERS

SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Output voltage range applied in high or low state, $V_O$ (see Notes 1 and 2) .....	-0.5 V to $V_{CC} + 0.5$ V
Voltage range applied to any output in the power-off state, $V_O$ (see Note 1) .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 50$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): D package .....	73°C/W
DB package .....	82°C/W
DGV package .....	120°C/W
NS package .....	64°C/W
PW package .....	108°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  2. This value is limited to 5.5 V maximum.
  3. The package thermal impedance is calculated in accordance with JESD 51-7.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# SN54LV166A, SN74LV166A 8-BIT PARALLEL-LOAD SHIFT REGISTERS

SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

## recommended operating conditions (see Note 4)

		SN54LV166A		SN74LV166A		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2	5.5	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	1.5		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7	V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7	V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7	V <sub>CC</sub> × 0.7		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V		0.5	0.5	V
		V <sub>CC</sub> = 2.3 V to 2.7 V		V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 3 V to 3.6 V		V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 4.5 V to 5.5 V		V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3	
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V		-50	-50	μA
		V <sub>CC</sub> = 2.3 V to 2.7 V		-2	-2	mA
		V <sub>CC</sub> = 3 V to 3.6 V		-6	-6	
		V <sub>CC</sub> = 4.5 V to 5.5 V		-12	-12	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V		50	50	μA
		V <sub>CC</sub> = 2.3 V to 2.7 V		2	2	mA
		V <sub>CC</sub> = 3 V to 3.6 V		6	6	
		V <sub>CC</sub> = 4.5 V to 5.5 V		12	12	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V		200	200	ns/V
		V <sub>CC</sub> = 3 V to 3.6 V		100	100	
		V <sub>CC</sub> = 4.5 V to 5.5 V		20	20	
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LV166A			SN74LV166A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1			V <sub>CC</sub> -0.1			V
	I <sub>OH</sub> = -2 mA	2.3 V	2			2			
	I <sub>OH</sub> = -6 mA	3 V	2.48			2.48			
	I <sub>OH</sub> = -12 mA	4.5 V	3.8			3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V to 5.5 V			0.1			0.1	V
	I <sub>OL</sub> = 2 mA	2.3 V			0.4			0.4	
	I <sub>OL</sub> = 6 mA	3 V			0.44			0.44	
	I <sub>OL</sub> = 12 mA	4.5 V			0.55			0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±1			±1	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			20			20	μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V				5			5	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		1.6			1.6		pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# SN54LV166A, SN74LV166A 8-BIT PARALLEL-LOAD SHIFT REGISTERS

SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

timing requirements over recommended operating free-air temperature range,  $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$  (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		SN54LV166A		SN74LV166A		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	$\overline{\text{CLR}}$ low	8	9	9	9	ns	
		CLK high or low	8.5	9	9	9		
$t_{su}$	Setup time	CLK INH before CLK $\uparrow$	7	7	7	7	ns	
		Data before CLK $\uparrow$	6.5	8.5	8.5	8.5		
		SH/ $\overline{\text{LD}}$ before CLK $\uparrow$	7	8.5	8.5	8.5		
		SER before CLK $\uparrow$	8.5	9.5	9.5	9.5		
$t_h$	Hold time	$\overline{\text{CLR}}\uparrow$ inactive before CLK $\uparrow$	6	7	7	7	ns	
		Data after CLK $\uparrow$	-0.5	0	0	0		

timing requirements over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		SN54LV166A		SN74LV166A		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	$\overline{\text{CLR}}$ low	6	7	7	7	ns	
		CLK high or low	6	7	7	7		
$t_{su}$	Setup time	CLK INH before CLK $\uparrow$	5	5	5	5	ns	
		Data before CLK $\uparrow$	5	6	6	6		
		SH/ $\overline{\text{LD}}$ before CLK $\uparrow$	5	6	6	6		
		SER before CLK $\uparrow$	5	6	6	6		
$t_h$	Hold time	$\overline{\text{CLR}}\uparrow$ inactive before CLK $\uparrow$	4	4	4	4	ns	
		Data after CLK $\uparrow$	0	0	0	0		

timing requirements over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		SN54LV166A		SN74LV166A		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration	$\overline{\text{CLR}}$ low	5	5	5	5	ns	
		CLK high or low	4	4	4	4		
$t_{su}$	Setup time	CLK INH before CLK $\uparrow$	3.5	3.5	3.5	3.5	ns	
		Data before CLK $\uparrow$	4.5	4.5	4.5	4.5		
		SH/ $\overline{\text{LD}}$ before CLK $\uparrow$	4	4	4	4		
		SER before CLK $\uparrow$	4	4	4	4		
$t_h$	Hold time	$\overline{\text{CLR}}\uparrow$ inactive before CLK $\uparrow$	3.5	3.5	3.5	3.5	ns	
		Data after CLK $\uparrow$	1	1	1	1		

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



# SN54LV166A, SN74LV166A 8-BIT PARALLEL-LOAD SHIFT REGISTERS

SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

**switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV166A		SN74LV166A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			$C_L = 15\text{ pF}$	50*	105*		45*		45		MHz
			$C_L = 50\text{ pF}$	40	80		35		35		
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	$Q_H$	$C_L = 15\text{ pF}$		8.8*	16*	1*	18*	1	18	ns
$t_{\text{pd}}$	CLK				9.2*	19.8*	1*	22*	1	22	
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	$Q_H$	$C_L = 50\text{ pF}$		11.3	19.5	1	22	1	22	ns
$t_{\text{pd}}$	CLK				11.8	23.3	1	26	1	26	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV166A		SN74LV166A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			$C_L = 15\text{ pF}$	65*	150*		55*		55		MHz
			$C_L = 50\text{ pF}$	60	120		50		50		
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	$Q_H$	$C_L = 15\text{ pF}$		6.3*	12.5*	1*	15*	1	15	ns
$t_{\text{pd}}$	CLK				6.6*	15.4*	1*	18*	1	18	
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	$Q_H$	$C_L = 50\text{ pF}$		7.9	16.3	1	18.5	1	18.5	ns
$t_{\text{pd}}$	CLK				8.3	18.9	1	21.5	1	21.5	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV166A		SN74LV166A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\text{max}}$			$C_L = 15\text{ pF}$	110*	205*		90*		90		MHz
			$C_L = 50\text{ pF}$	95	160		85		85		
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	$Q_H$	$C_L = 15\text{ pF}$		4.6*	8.6*	1*	10*	1	10	ns
$t_{\text{pd}}$	CLK				4.8*	9.9*	1*	11.5*	1	11.5	
$t_{\text{PHL}}$	$\overline{\text{CLR}}$	$Q_H$	$C_L = 50\text{ pF}$		5.7	10.6	1	12	1	12	ns
$t_{\text{pd}}$	CLK				6.1	11.9	1	13.5	1	13.5	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**operating characteristics,  $T_A = 25^\circ\text{C}$**

PARAMETER	TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{\text{pd}}$ Power dissipation capacitance	$C_L = 50\text{ pF}$ , $f = 10\text{ MHz}$	3.3 V	39.1	pF
		5 V	44.5	

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

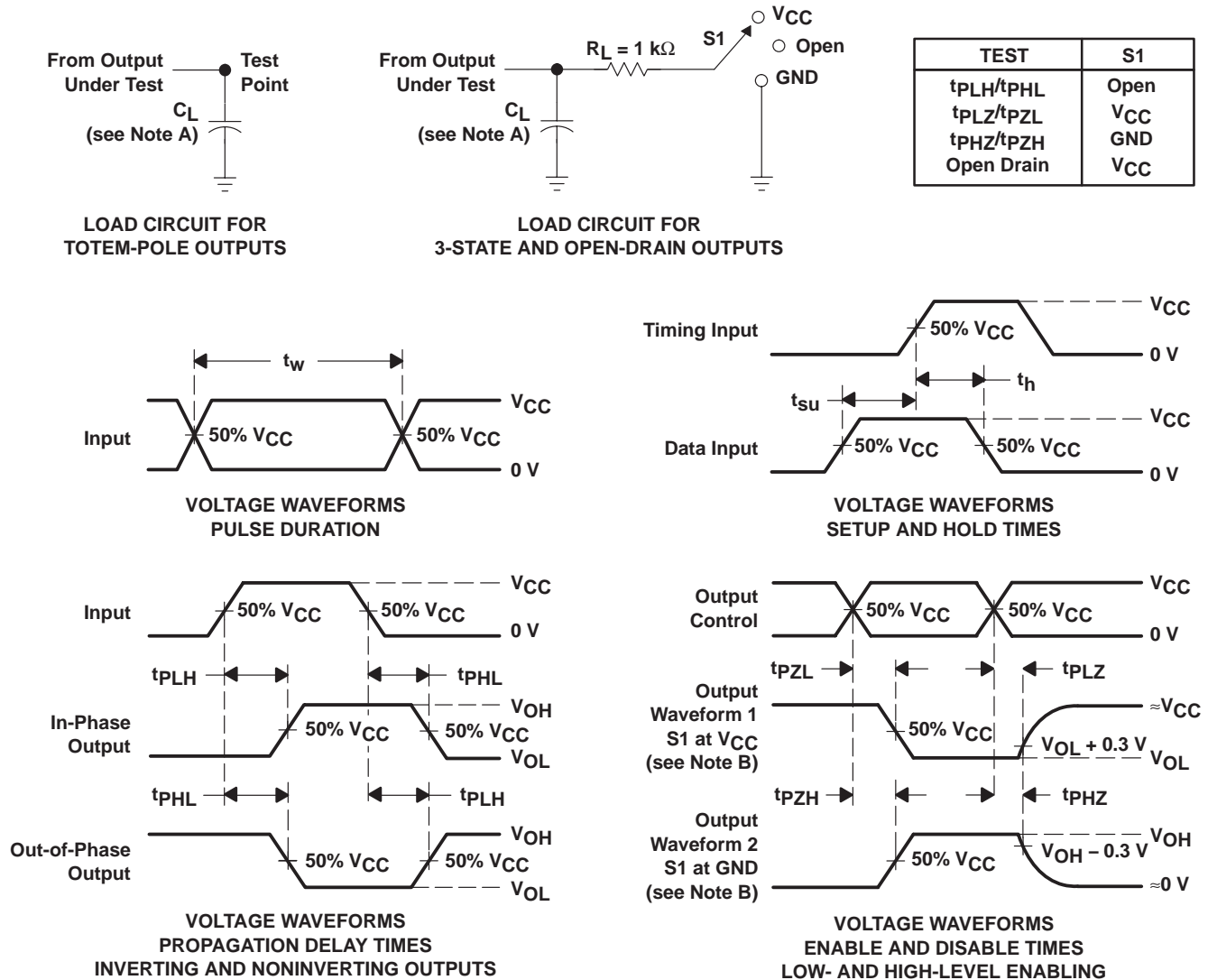


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# SN54LV166A, SN74LV166A 8-BIT PARALLEL-LOAD SHIFT REGISTERS

SCLS456C – FEBRUARY 2001 – REVISED APRIL 2005

## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV166AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples
SN74LV166ADBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples
SN74LV166ADGVR	ACTIVE	TVSOP	DGV	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples
SN74LV166ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples
SN74LV166ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV166A	Samples
SN74LV166APW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples
SN74LV166APWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples
SN74LV166APWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV166A	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV166ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV166ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV166ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV166ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV166APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV166ADBR	SSOP	DB	16	2000	356.0	356.0	35.0
SN74LV166ADGVR	TVSOP	DGV	16	2000	356.0	356.0	35.0
SN74LV166ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LV166ANSR	SO	NS	16	2000	356.0	356.0	35.0
SN74LV166APWR	TSSOP	PW	16	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LV166AD	D	SOIC	16	40	507	8	3940	4.32
SN74LV166APW	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# DB0016A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4220763/A 05/2022

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220763/A 05/2022

NOTES: (continued)

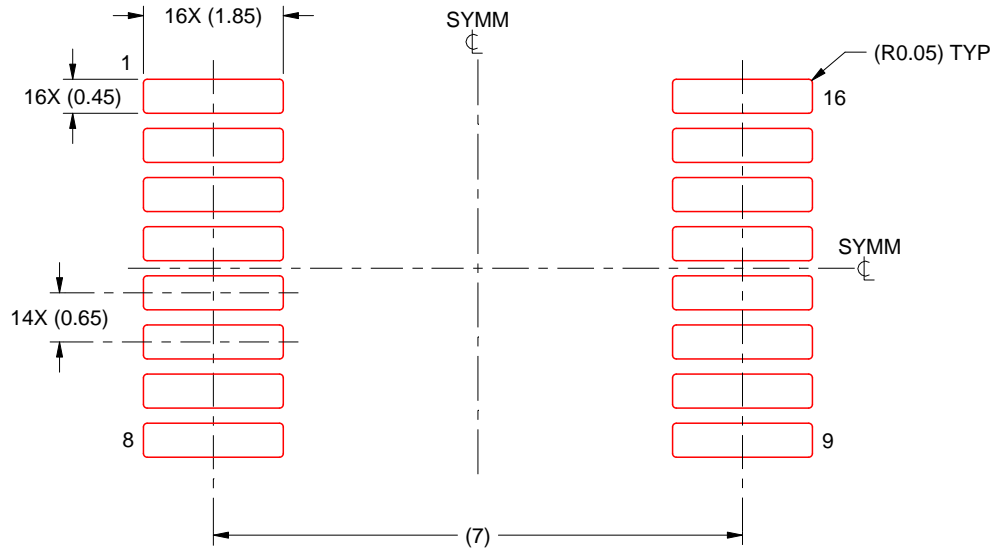
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



# PACKAGE OUTLINE

## NS0016A

### SOP - 2.00 mm max height

SOP



4220735/A 12/2021

#### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



# EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2022, Texas Instruments Incorporated